

FOR IMMEDIATE RELEASE

Issue Price of the 4.5% Senior Notes for U.S. Federal Income Tax Purposes

Singapore – 29 April 2013 – STATS ChipPAC Ltd. (“STATS ChipPAC” or the “Company” – SGX-ST: STATSchP), a leading provider of advanced semiconductor packaging and test services, refers to the exchange offer memorandum dated February 14, 2013, with respect to our offer to exchange (the “Exchange Offer”) our 7.5% Senior Notes due 2015 for our 4.5% Senior Notes due 2018 (the “New Notes”), and the offering circular dated March 4, 2013, with respect to our offering US\$255,000,000 in aggregate principal amount of New Notes.

Based on the information reasonably available to STATS ChipPAC, the Company intends to take the position that the issue price of the New Notes equals their stated principal amount for U.S. Federal Income Tax Purposes. There can be no assurance the IRS will not take a different position from ours or that any such position would be sustained. Holders should consult their tax advisors regarding the issue price of the New Notes and other tax consequences of the foregoing position by the Company.

Unless otherwise defined, all capitalised terms shall bear the same meanings as in the Exchange Offer Memorandum.

Forward-Looking Statements

Certain statements in this release, including statements regarding the Company’s position on the issue price of the New Notes, are forward-looking statements. All forward-looking statements involve a number of risks and uncertainties that could cause actual results to differ materially from expectations. Factors that could cause actual results to differ include factors discussed in its reports filed with the Securities Exchange Securities Trading Limited (“SGX-ST”). You should not unduly rely on such statements. We do not intend, and do not assume any obligation, to update any forward-looking statements to reflect subsequent events or circumstances.

About STATS ChipPAC Ltd.

STATS ChipPAC Ltd. (SGX-ST Code: S24) is a leading service provider of semiconductor packaging design, assembly, test and distribution solutions in diverse end market applications including communications, digital consumer and computing. With global headquarters in Singapore, STATS ChipPAC has design, research and development, manufacturing or customer support offices throughout Asia, the United States and Europe. STATS ChipPAC is listed on the SGX-ST. Further information is available at www.statschippac.com. Information contained in this website does not constitute a part of this release.

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